

### **In the Specification**

Please change the title to -- Electronic Assembly Having Semiconductor Component With Polymer Support Member And Method Of Fabrication --.

On page 2, line 1, add the following:

#### **--Cross Reference To Related Applications**

This application is a continuation of Serial No. 09/653,366 filed 09/01/2000, which is a division of Serial No. 09/440,380 filed 11/15/1999, Patent No. 6,180,504 B1, which is a division of Serial No. 09/384,783 filed 08/27/1999, Patent No. 6,118,179.